

AMENDMENTS TO THE CLAIMS

1-5. (Canceled)

6. (Currently amended) ~~A semiconductor chip having a plurality of chip connection portions formed on a surface thereof,~~

~~wherein the plurality of chip connection portions arranged in positions standardized among a plurality of predetermined types of semiconductor chips. A second semiconductor chip having second chip connection portions formed on a surface thereof and bonded to a chip bonding region arranged on a surface of a first semiconductor chip, the second chip connection portions connected to first chip connection portions arranged in the chip bonding region,~~

~~wherein the second chip connection portions are arranged along at least one pair of opposite sides of a region corresponding to the chip bonding region, a distance between the second chip connection portions arranged along a first side of said at least one pair of opposite sides,~~

~~wherein at least part of the second chip connection portions are common to a plurality of predetermined types of second semiconductor chips so as to be used for input/output of signals having identical specifications, and~~

~~wherein, on the plurality of predetermined types of second semiconductor chips, the second chip connection portions are arranged in positions corresponding to standardized positions.~~

7. (Currently amended) A The second semiconductor chip as claimed in claim 6,

wherein the plurality of predetermined types of second semiconductor chips have identical functions but are of different grades.

8. ~~(Currently amended) A semiconductor chip having, on a surface thereof, a chip connection region that fits any of a plurality of predetermined types of semiconductor chips,~~

~~wherein, in the chip connection region, chip connection portions are formed in standardized positions so as to fit any of the plurality of predetermined types of semiconductor chips, and the chip connection portions are arranged along an edge of the chip connection region, and~~

~~wherein the chip connection region is rectangular in shape, and the chip connection portions are arranged along opposite sides of the chip connection region~~ A semiconductor chip having, on a surface thereof, a chip connection region that fits any of a plurality of predetermined types of semiconductor chips,

wherein, in the chip connection region, chip connection portions are formed in standardized positions so as to fit any of the plurality of predetermined types of semiconductor chips, and the chip connection portions are arranged along an edge of the chip connection region,

wherein the semiconductor chip is rectangular in shape, and

wherein the chip connection portions are arranged along at least one pair of opposite sides of the chip connection region, a distance between the chip connection portions arranged along a first side of said at least one pair of opposite sides is shorter than a distance from the chip connection portions arranged along said first side of said at least one pair of opposite sides to the chip connection portions arranged along a

second side of said at least one pair of opposite sides, and at least part of the chip connection portions are common to the plurality of predetermined types of semiconductor chips so as to be used for input/output of signals having identical specifications.

9. (Currently amended) ~~The semiconductor chip having a plurality of chip connection portions formed on a surface thereof,~~

~~wherein the plurality of chip connection portions are arranged in positions standardized among a plurality of predetermined types of semiconductor chips, and are arranged along an edge of the semiconductor chip.~~ A semiconductor chip having second chip connection portions formed on a surface thereof and bonded to a chip bonding region arranged on a surface of a first semiconductor chip, the second chip connection portions connected to a first chip connection portions arranged in the chip bonding region,

wherein the second chip connection portions are disposed along an edge of the second semiconductor chip and are arranged along at least one pair of opposite sides of a region corresponding to the chip bonding region, a distance between the second chip connection portions arranged along said first side of said at least one pair of opposite sides to the second chip connection portions arranged along a second side of said at least one pair of opposite sides,

wherein at least part of the second chip connection portions are common to a plurality of predetermined types of second semiconductor chips so as to be used for input/output of signals having identical specifications, and